



APPENDIX

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Please amend claim 1 as follows:

- 1 1. (Amended) A bond pad assembly comprising:
 - 2 a bond pad;
 - 3 a trace that applies an attractive force to solder placed on the pad,
 - 4 said trace coupled to said pad and extending away from said pad in a first
 - 5 direction; and
 - 6 a trace stub to counteract the attractive force applied by the trace,
 - 7 said trace stub coupled to said pad and extending away from said pad in a
 - 8 direction other than said first direction.
- 1 10. (Amended) A bonding system comprising:
 - 2 a bond pad;
 - 3 a trace coupled to said bond pad and extending away from said
 - 4 pad; and
 - 5 an element adapted to counteract [the] an attractive [forces] force
 - 6 applied by the trace to solder placed on the bond pad.
- 1 16. (Amended) The system of claim 10 wherein the attractive [forces]
2 force applied by the trace to said solder [ball arise] arises from [the configuration
- 3 of] said trace being coupled to and extending away from said bond pad, said
- 4 element adapted to emulate said trace.